

# Board-level Troubleshooting Quiz

TIPL 1901

TI Precision Labs – Op Amps

# Multiple Choice

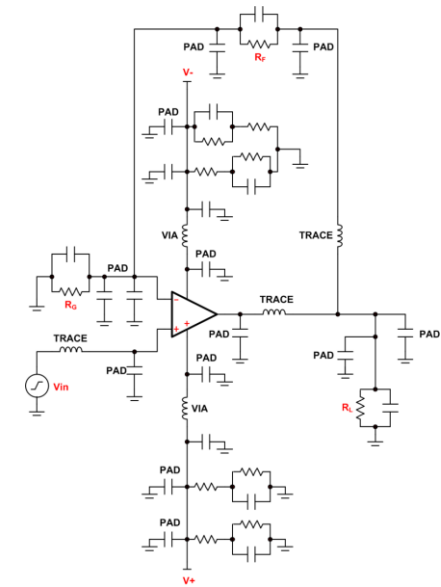
- Of the following troubleshooting technique which is recommended to occur first?
  - a. A-B-A Swap
  - b. Optical Inspection
  - c. Circuit Analysis (probing test points)
  - d. Request Failure Analysis
  
- Identify the benefits which apply to the A-B-A swap.
  - a. Rule out a device under test
  - b. Resolve assembly level anomalies
  - c. Confirm in an anomaly follows a device under test
  - d. All of the above

# Multiple Choice

- It is recommended to re-solder device (A) to the original PCB after verifying the device (A) on a passing PCB.
  - a. True
  - b. False
- Why is a dry-bake recommend prior to de-soldering plastic mold compound products?
  - a. Reflow cold solder joints
  - b. Melt flux
  - c. Remove moisture
  - d. None of the above

# Multiple Choice

- Which of the following is **not** an advantage to cleaning a PCB?
  - a. Remove excess solder flux
  - b. Mitigate long term corrosion
  - c. Reduce parasitic paths
  - d. Reflow cold solder joints
  
- Which of the following is **not** an example of a component that can attribute to “extra” circuit elements?
  - a. Contamination
  - b. Thermocouples
  - c. capacitors
  - d. An ideal operational amplifier



# Solutions

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